

*See
amended*

67. (New) A device manufacturing method, comprising the steps of:

performing an exposure process on a substrate by use of an exposure apparatus
as recited in claim 61; and

performing an etching process to the exposed substrate. --

REMARKS

Applicant requests favorable consideration and allowance of the subject application in view of the preceding amendments and the following remarks.

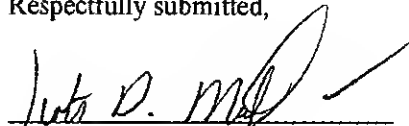
Claims 25-67 are presented for consideration. Claims 25, 31, 36, 38, 40, 47, 52, 57, 59, and 61 are independent.

Claims 47-67 are being added to provide an additional scope of protection. It is submitted that these claims are consonant with the elected claims of Group II.

Due consideration and prompt passage to issue are respectfully requested.

Applicant's undersigned attorney may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should be directed to our address listed below.

Respectfully submitted,



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